

US00D505400S

(12) **United States Design Patent** (10) **Patent No.:** **US D505,400 S**
Kawafuji et al. (45) **Date of Patent:** **** May 24, 2005**

(54) **SEMICONDUCTOR DEVICE**

D448,740 S * 10/2001 Iwasaki et al. D13/182
D472,530 S * 4/2003 Iwasaki et al. D13/182

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FOREIGN PATENT DOCUMENTS

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JP 098 288 601 6/1997
JP 106 57 0100 4/2000

(**) Term: **14 Years**

* cited by examiner

(21) Appl. No.: **29/213,816**

Primary Examiner—Stella Reid

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(22) Filed: **Sep. 24, 2004**

(74) *Attorney, Agent, or Firm*—Sughrue Mion, PLLC

(30) **Foreign Application Priority Data**

Mar. 26, 2004 (JP) 2004-009136

(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

(51) **LOC (7) Cl.** **13-03**

DESCRIPTION

(52) **U.S. Cl.** **D13/182**

(58) **Field of Search** D13/182; 174/52.1,
174/52.2, 52.4; 257/666, 669, 675, 676,
678, 690, 692, 696, 697, 730, 787; 361/773,
820; 438/64, 65

FIG. 1 is a front, top and right side perspective view of a semiconductor device, showing our new design;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a rear elevational view thereof;

FIG. 4 is a top plan view thereof;

FIG. 5 is a bottom plan view thereof;

FIG. 6 is a left side elevational view thereof;

FIG. 7 is a right side elevational view thereof; and,

FIG. 8 is an enlarged cross-sectional view thereof and, taken along line 8—8 of FIG. 2, with the internal system omitted.

(56) **References Cited**

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D448,739 S * 10/2001 Iwasaki et al. D13/182

1 Claim, 4 Drawing Sheets

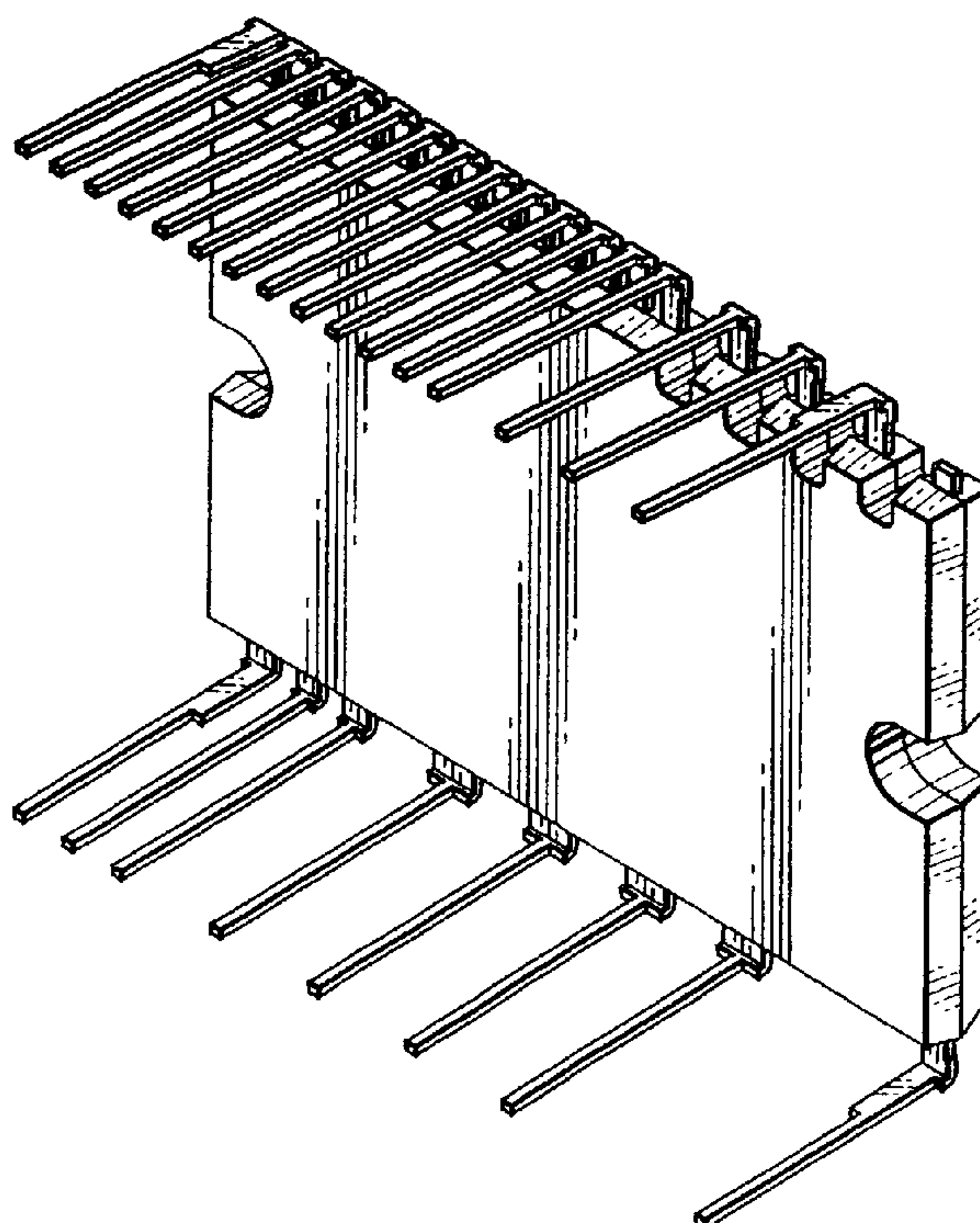


FIG. 1

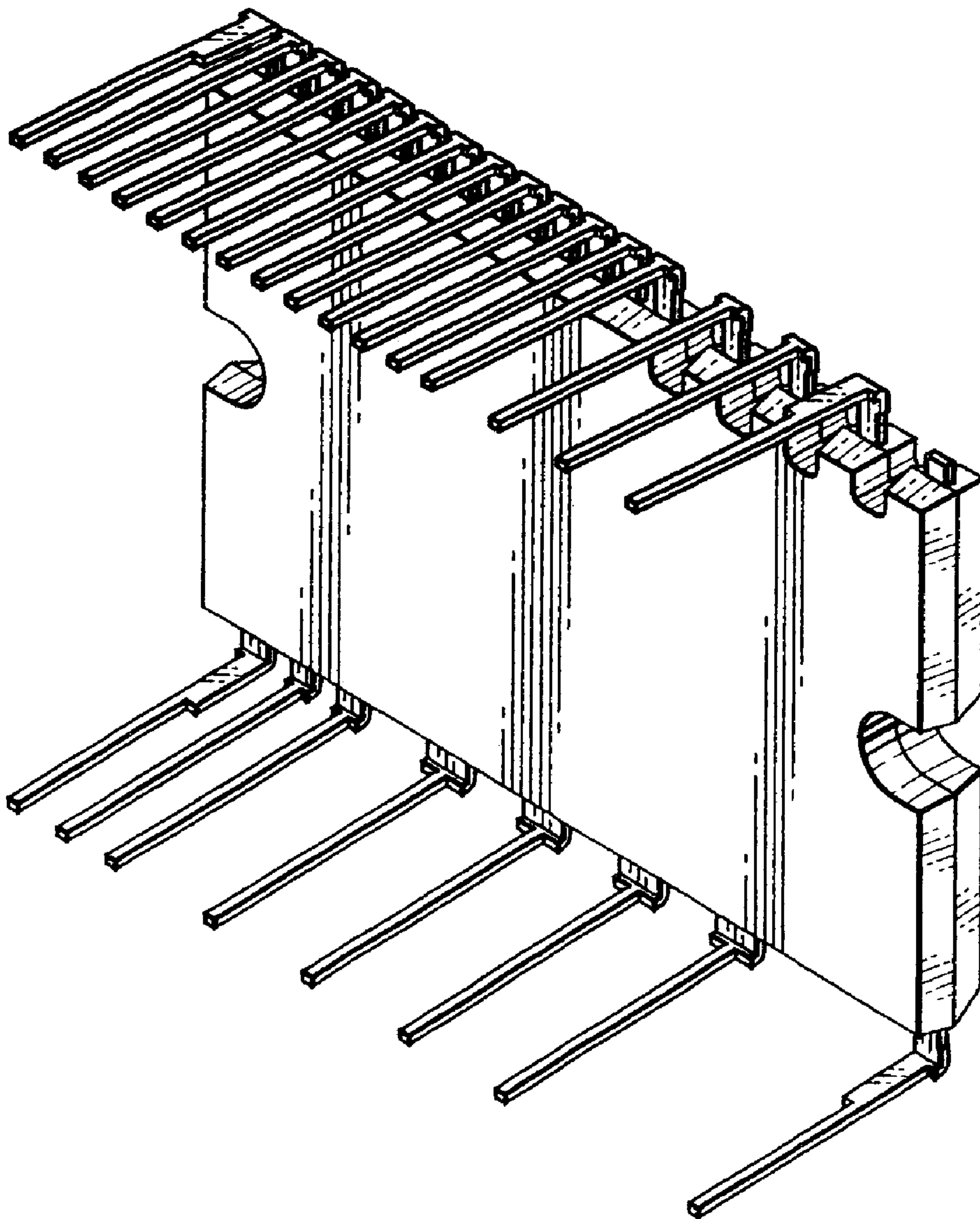


FIG.2

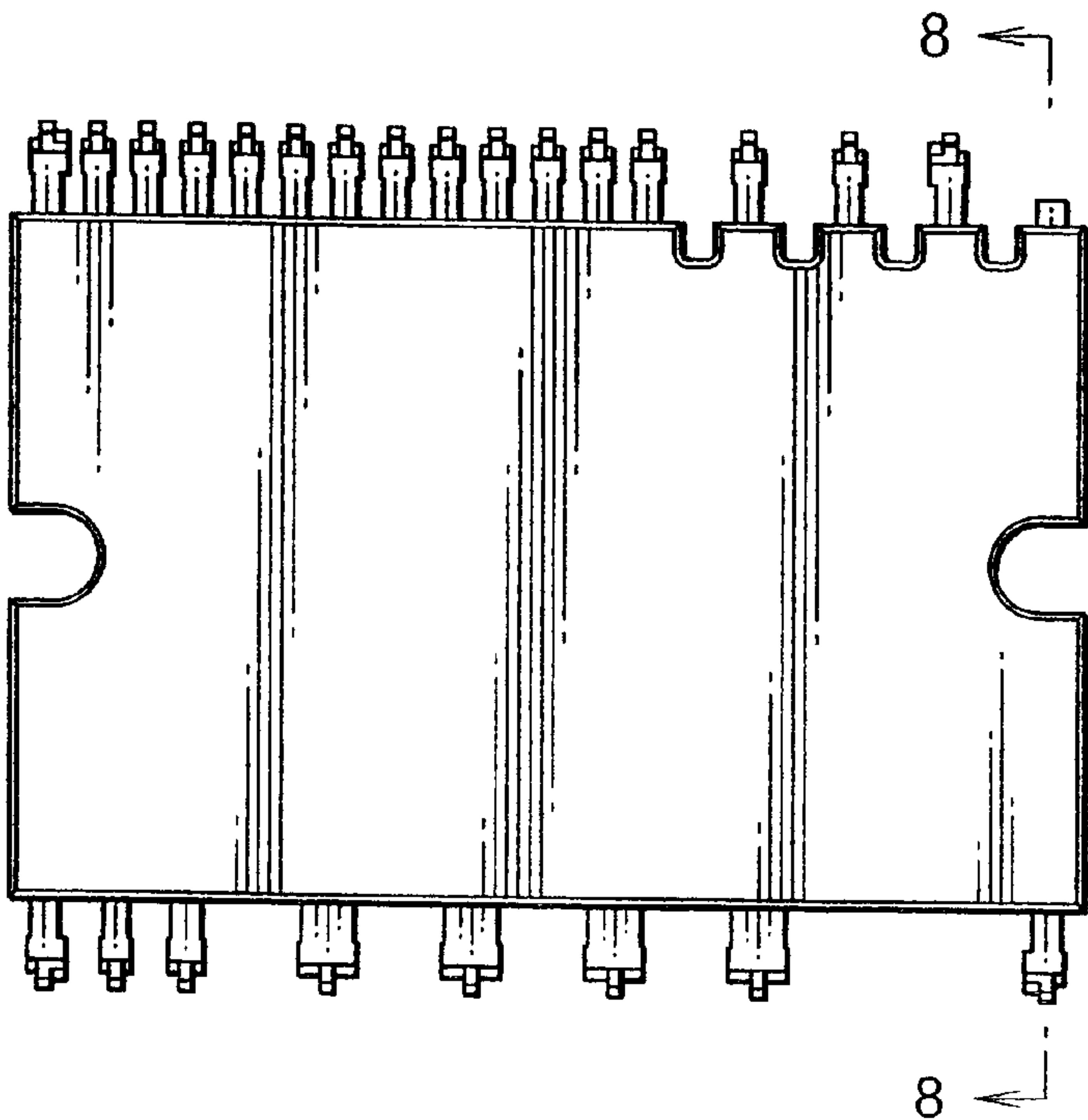


FIG.3

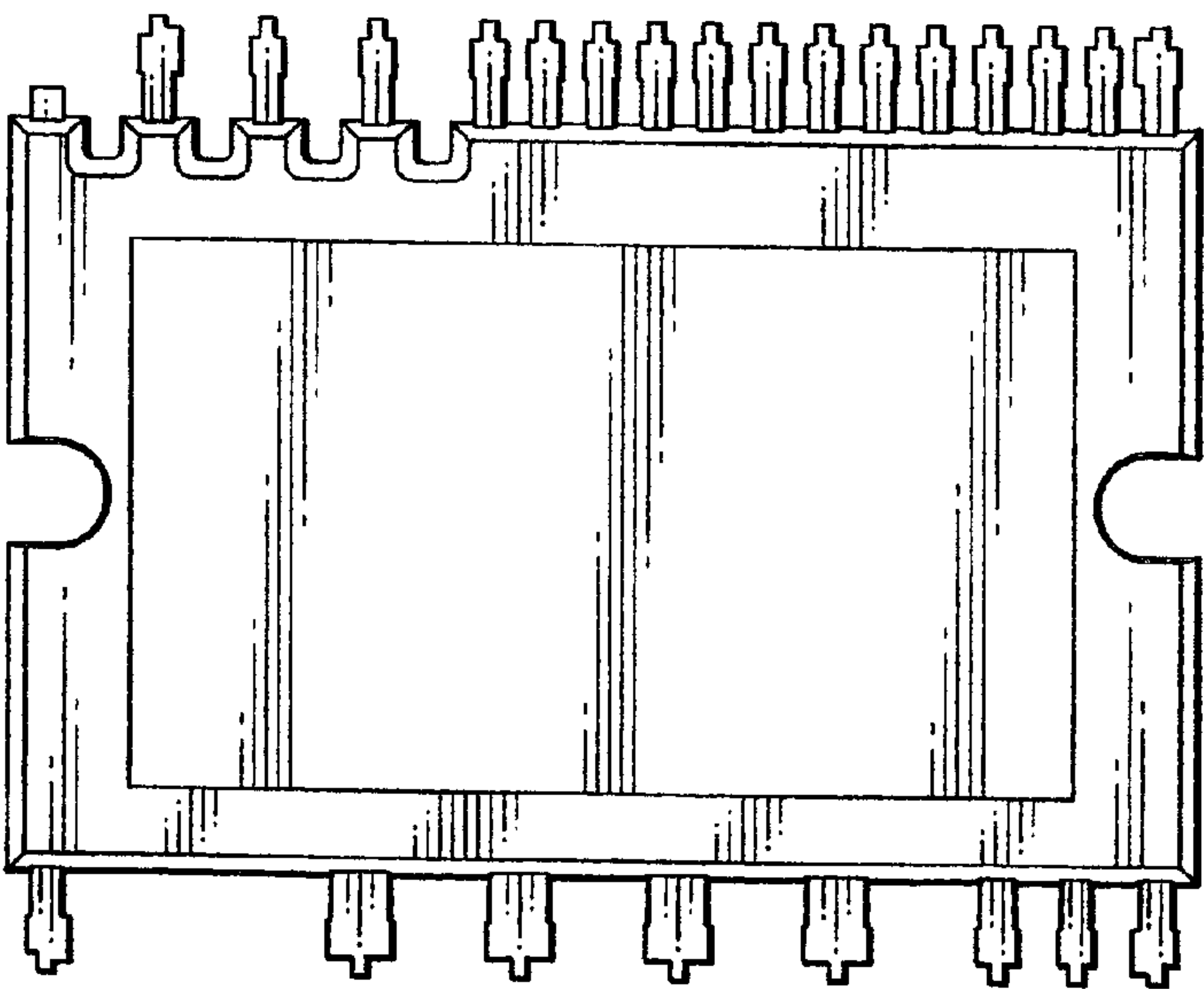


FIG.4

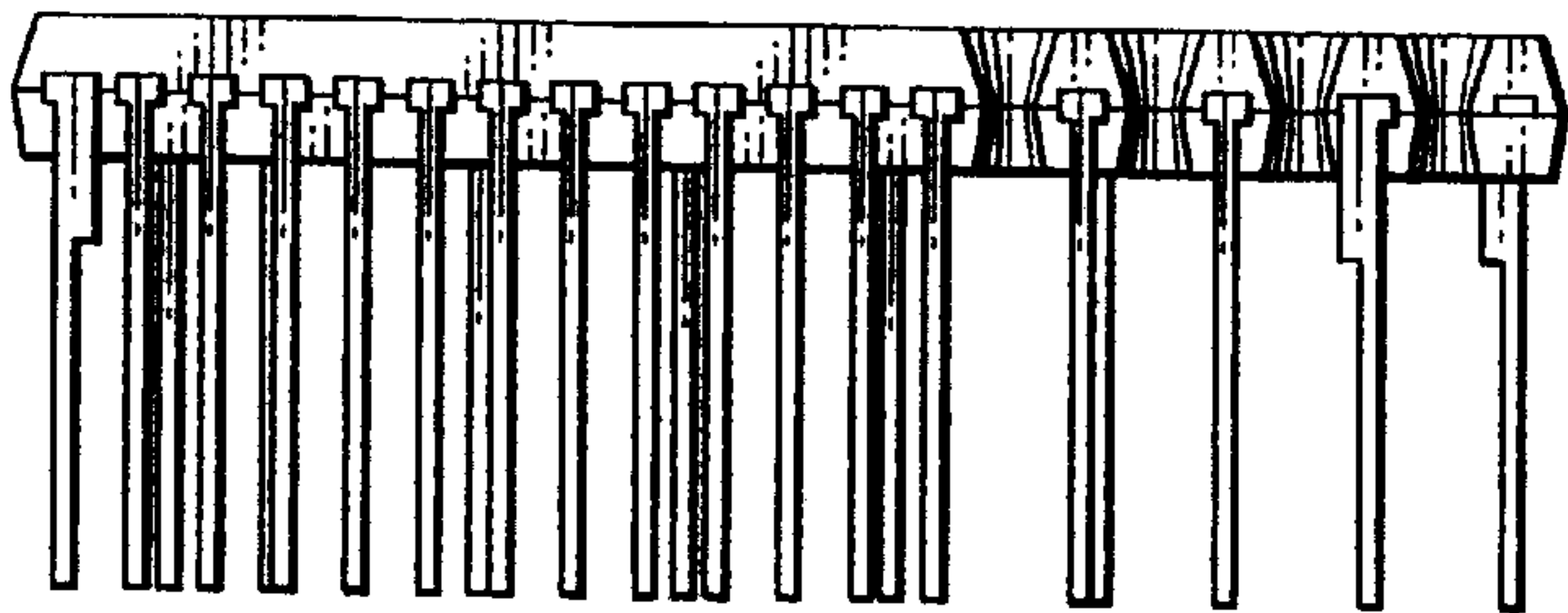


FIG.5

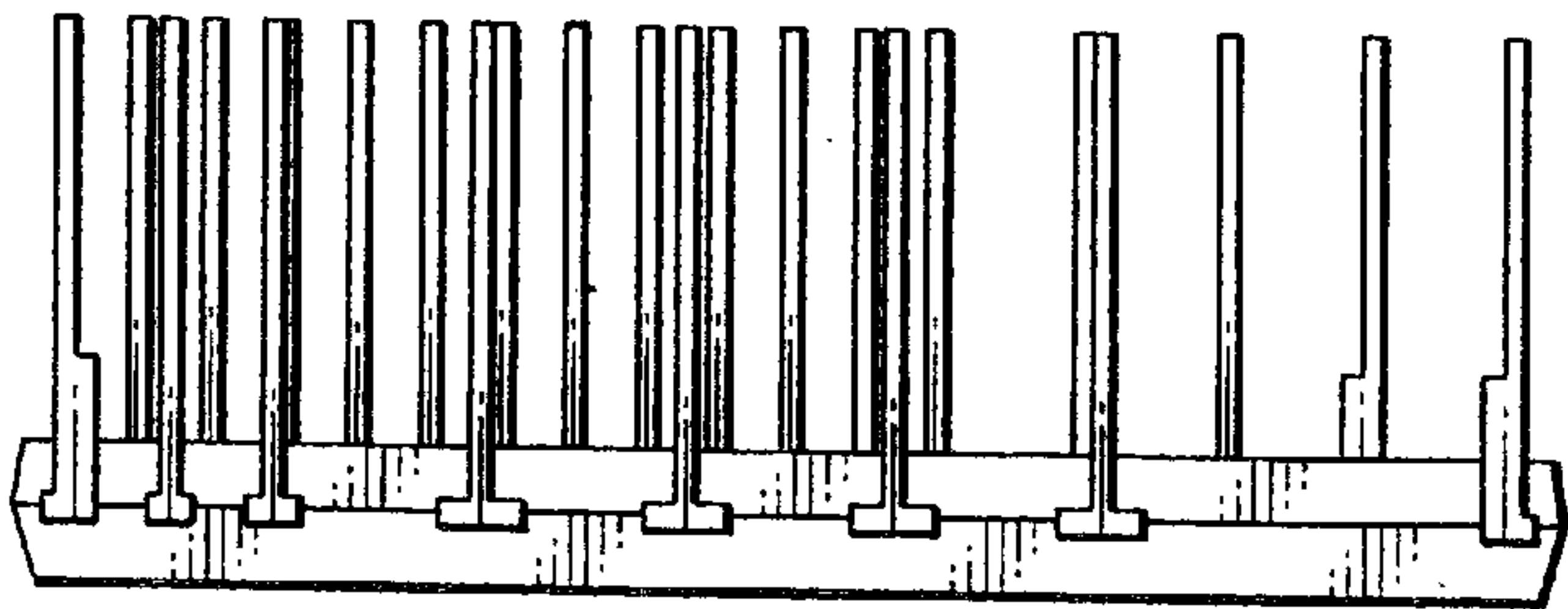


FIG.6

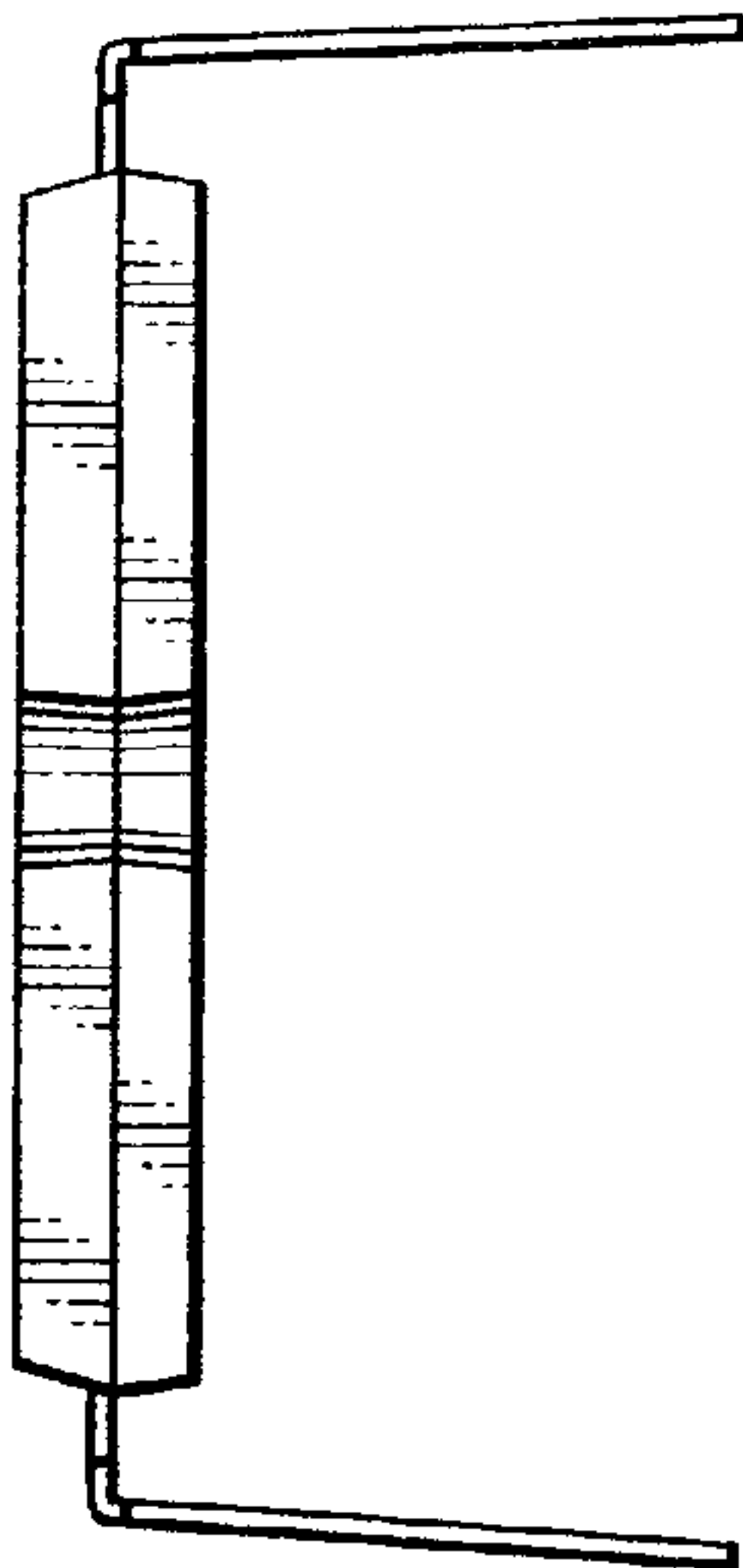


FIG.7

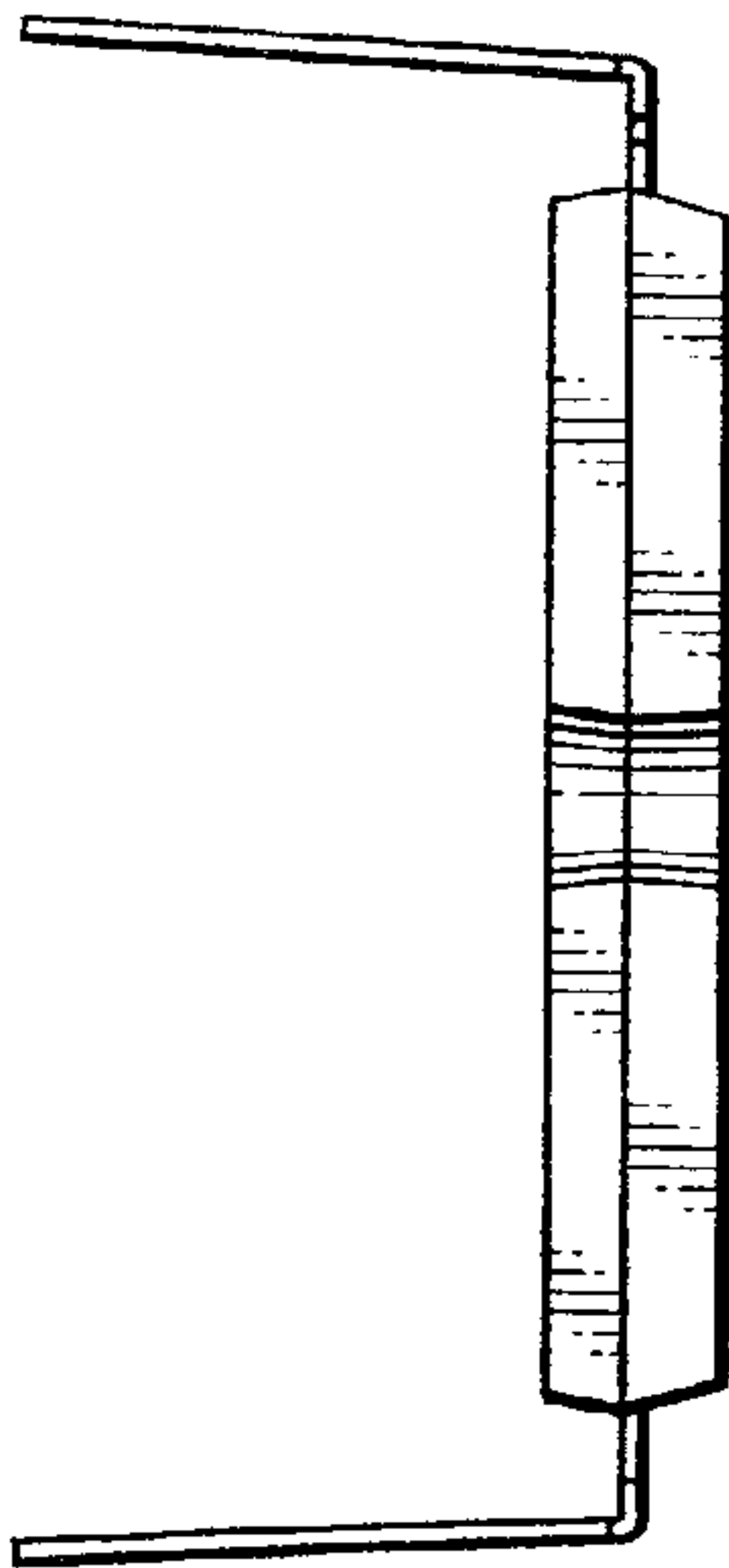


FIG.8

